



Material Content Data Sheet



Sales Product Name		IPG16N10S4L-61A		Issued		31. July 2018		
MA#		MA002193054						
Package		PG-TDSON-8-10		Weight*		98.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.669	0.68	0.68	6814	6814
chip_2	inorganic material	silicon	7440-21-3	0.669	0.68	0.68	6814	6814
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		142	
	non noble metal	iron	7439-89-6	0.046	0.05		473	
	non noble metal	copper	7440-50-8	46.380	47.28	47.34	472582	473197
	non noble metal	aluminium	7429-90-5	0.798	0.81	0.81	8136	8136
wire	organic material	carbon black	1333-86-4	0.091	0.09		930	
	plastics	epoxy resin	-	6.482	6.60		66049	
encapsulation	inorganic material	silicondioxide	60676-86-0	39.076	39.82	46.51	398155	465134
	non noble metal	tin	7440-31-5	1.396	1.42	1.42	14228	14228
leadfinish	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6145	6160
plating	non noble metal	tin	7440-31-5	0.038	0.04		390	
	noble metal	silver	7440-22-4	0.048	0.05		488	
solder	non noble metal	lead	7439-92-1	1.829	1.86	1.95	18639	19517
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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